

S/N 09/854,539

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Intel Corporation et al.

Examiner: Ginette Peralta

Serial No.: 09/854,539

Group Art Unit: 2814

Filed: May 14, 2001

Docket No.: 884.415US1

Title: POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR
USE IN MICROELECTRONIC CIRCUIT PACKAGING

Assignee: Intel Corporation

Customer No: 21186

RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on October 20, 2004. Please amend the above-identified patent application as follows.